



BOARD'S DRILL SCHEDULE Drill Size - Inches

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.02	459	YES	---	
⊞	.041	54	YES	---	
⊕	.047244094	93	YES	---	
⊞	.051181102	7	NO	---	
⊖	.05511811	22	YES	---	
⊞	.07480315	24	YES	---	
⊕	.16535433	6	NO	---	
□	.17716535	8	NO	---	

Layer Order

- Film 1 - Top
- Film 2 - Power
- Film 3 - Signal
- Film 4 - Power
- Film 5 - Power
- Film 6 - Signal
- Film 7 - Power
- Film 8 - Bottom

Board Characteristics

0. Material - RF4, 0.062" Thick PCB
1. Minimum trace width and clearance: 8 mils
2. 1 Oz Copper on Top, Bottom, and Power Layers
3. 0.5 Oz Copper on inner Signal Layers: Layer 3, Layer 6
4. Silkscreen on both Sides.
5. Soldermask on Top and Bottom, as per Gerbers

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING	CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
	APPROVALS	DATE	TITLE HELIX Monitor Board Specification Drawing			
DRAWN M. Bogdan	3/14/2022					
CHECKED M. Bogdan	3/14/2022	SIZE	FSCM NO.	DWG. NO.	2977	REV.
ISSUED						B
TREATMENT						
FINISH						
SIMILAR TO	ACT. WT	CALC WT	SCALE	1 / 1		SHEET